# **MA2S376**

## Silicon epitaxial planar type

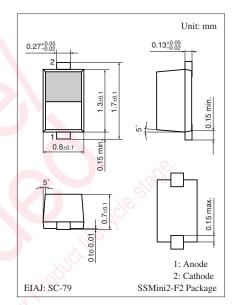
#### For VCO of a UHF radio

#### ■ Features

- ullet Small series resistance  $r_D$
- SS-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	$V_R$	6	V	
Junction temperature	Tj	150	°C	
Storage temperature	$T_{stg}$	-55 to +150	°C	



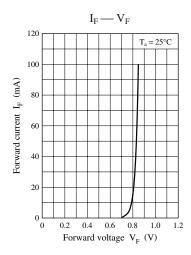
Marking Symbol: H

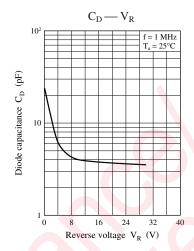
#### ■ Electrical Characteristics $T_a=25$ °C $\pm 3$ °C

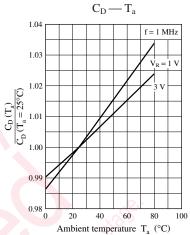
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current	$I_R$	$V_R = 6 \text{ V}$	100	0,	10	nA
Diode capacitance	C <sub>D(1V)</sub>	$V_R = 1 \text{ V, f} = 1 \text{ MHz}$	14.00	)-	16.00	pF
	C <sub>D(3V)</sub>	$V_R = 3 \text{ V, f} = 1 \text{ MHz}$	6.80		8.90	
Series resistance *	$r_{\mathrm{D}}$	$C_D = 9 \text{ pF, } f = 470 \text{ MHz}$			0.3	Ω

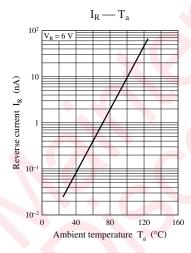
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. Absolute frequency of input and output is 470 MHz.
- 3. \*: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER









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